

Briefs: STM delivers new wireless-phone chip set

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A new multi-chip package designed for 3G and CDMA mobile phones and carrying 1 GB of Flash memory was unveiled Thursday by STMicroelectronics.

The Swiss semiconductor said its MCP was developed in concert with vendors of operating systems and other chipsets to meet anticipated demand for third-generation multimedia applications as well as CDMA (Code-Division Multiple Access) digital phones.

The devices will be applied to such uses as Web surfing, phone cameras and video while keeping phones as small as possible.

The MCPs can be configured in a number of ways and carry 1 GB of NAND Flash memory and 512 MB of LPSDRAM (Low-Power Synchronous Dynamic RAM).

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